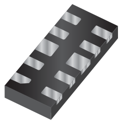
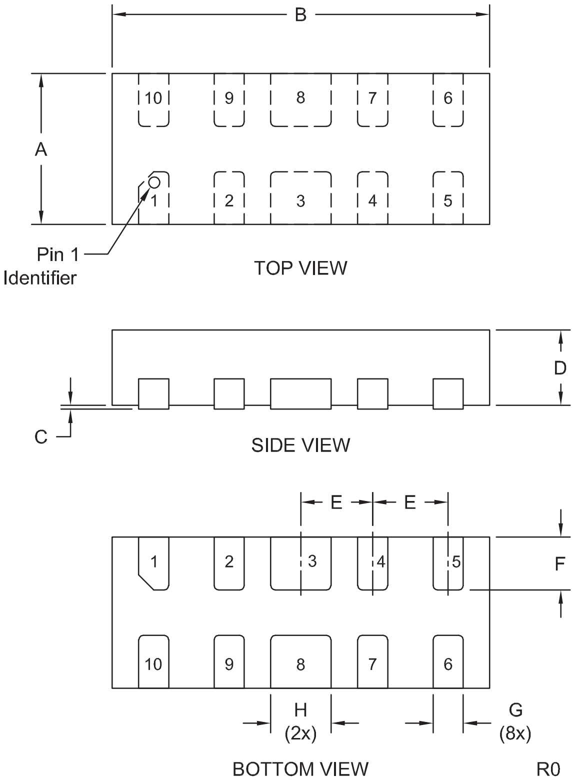
Package Details

TLM1031 Case



Mechanical Drawing



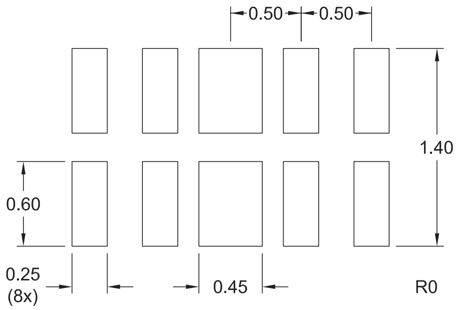
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.037	0.041	0.95	1.05
B	0.096	0.100	2.45	2.55
C	0.000	0.002	0.00	0.05
D	0.018	0.022	0.45	0.55
E	0.020		0.50	
F	0.012	0.016	0.30	0.40
G	0.006	0.010	0.15	0.25
H	0.014	0.018	0.35	0.45

TLM1031 (REV:R0)

Part Marking:
4-5 Character Alpha/Numeric Code

Lead Code:
Reference individual device datasheet.

Mounting Pad Geometry (Dimensions in mm)



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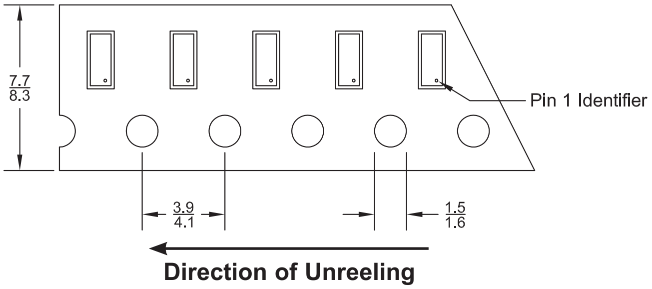
Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

7” Reel = 5,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	45,000	9x9x5	23x23x13	3	2
	19	95,000	9x9x9	23x23x23	6	3
	40	200,000	21x9x9	53x23x23	13	6
	104	520,000	27x9x17	69x23x43	34	16

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

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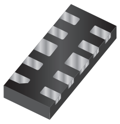
Material Composition Specification

TLM1031 Case



Device average mass . . . . **3.64 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.92%	0.07	Si	7440-21-3	1.92%	0.07	19,231
bond wire	gold	0.55%	0.02	Au	7440-57-5	0.55%	0.02	5,495
leadframe	Cu alloy	21.15%	0.77	Cu	7440-50-8	21.02%	0.765	210,165
				Cr	7440-47-3	0.05%	0.002	549
				Sn	7440-31-5	0.05%	0.002	549
				Zn	7440-66-6	0.03%	0.001	275
die attach	silver epoxy	0.25%	0.009	epoxy resin	Proprietary	0.19%	0.007	1,923
				Ag	7440-22-4	0.05%	0.002	549
encapsulation*	EMC GREEN	74.95%	2.728	silica	60676-86-0	57.69%	2.1	576,923
				epoxy resin	29690-82-2	7.14%	0.26	71,429
				phenol resin	9003-35-4	7.14%	0.26	71,429
				carbon black	1333-86-4	0.22%	0.01	2,198
				metal hydroxide	1309-42-8	2.75%	0.1	27,473
plating	matte tin	1.18%	0.043	Sn	7440-31-5	1.18%	0.043	11,813

*EMC GREEN molding compound is Halogen-Free.

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